

REMARKS

Applicant has carefully studied the outstanding Official Action. The present response is intended to be fully responsive to all points of rejection raised by the Examiner and is believed to place the application in condition for allowance. Favorable reconsideration and allowance of the application is respectfully requested.

Applicant wishes to thank the Examiner for the courtesy of an interview granted to Applicant's representative, Sanford T. Colb, on 26 June 2002. The Interview Summary Record states as follows:

"Applicant proposes amendment of either adding the limitation of "chip scale package" to independent claim 1 or cancel claim 1, to overcome the cited reference (e.g. Spaeth et al, 5,981,945). The Examiner needs further search and consideration.

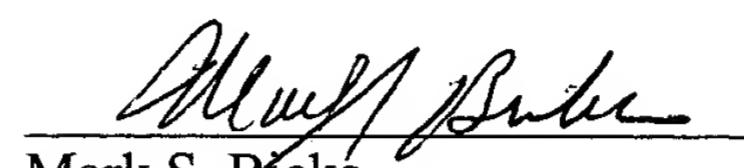
The purpose of this amendment is to add the above limitation to all of the independent claims of record. Specifically, the above limitation has been added to claim 1 and also to independent claims 20 and 38. The above limitation is already present in the remaining independent claims, namely claims 10 and 37.

In summary, in all claims now in the case, the package or packaging is now recited to be a chip scale package or packaging.

Applicant has carefully studied the remaining prior art of record herein and concludes that the invention as described and claimed in the present application is neither shown in nor suggested by the cited art.

In view of the foregoing remarks, all of the claims are believed to be in condition for allowance. Favorable reconsideration and allowance of the application is respectfully requested.

Respectfully submitted,



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MARKEUP COPY OF CLAIMS TO SHOW CHANGES MADE

1. (Twice Amended) A crystalline substrate based device comprising:

a crystalline substrate having formed thereon a microstructure; and

at least one transparent chip scale packaging layer which is sealed over said microstructure by means of an adhesive and defines therewith at least one gap between said crystalline substrate and said at least one chip scale packaging layer,

wherein said microstructure receives light via said at least one transparent packaging layer.

20. (Twice Amended) A method of producing a crystalline substrate based device comprising:

providing a microstructure on a substrate; and

adhesively sealing at least one chip scale packaging layer over said microstructure and at least partially spaced therefrom, thereby to define a gap between said microstructure and said at least one chip scale packaging layer,

wherein said at least one chip scale packaging layer is transparent.

38. (Amended) A crystalline substrate based device comprising:

a crystalline substrate having formed thereon a microstructure; and

at least one chip scale packaging layer which is sealed over said microstructure and defines therewith at least one gap between said crystalline substrate and said at least one packaging layer, the crystalline substrate, microstructure and chip scale packaging layer forming a chip scale package,

the chip scale package having a multiplicity of electrical contacts plated along edge surfaces thereof.



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APPLICATION NUMBER	FILING DATE	FIRST NAMED APPLICANT	ATTORNEY DOCKET NO.
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EXAMINER

ART UNIT

PAPER NUMBER

DATE MAILED:

INTERVIEW SUMMARY

All participants (applicant, applicant's representative, PTO personnel):

(1) Sarfond Colb (3)

(2) LVAIV TH 41 (4)

Date of Interview 6/26/02

Type: Telephonic Televideo Conference Personal (copy is given to applicant applicant's representative).

Exhibit shown or demonstration conducted: Yes No If yes, brief description:

Agreement was reached, was not reached.

Claim(s) discussed: all

Identification of prior art discussed: Spaeth et al. (5,381,945)

Description of the general nature of what was agreed to if an agreement was reached, or any other comments:

Applicant's proposed amendment of either adding the limitation of "chip scale package" to independent claim 1 or cancel claim 1, to overcome the cited reference (e.g. Spaeth et al. 5,381,945). The examiner need further search and consideration.

(A fuller description, if necessary, and a copy of the amendments, if available, which the examiner agreed would render the claims allowable must be attached. Also, where no copy of the amendments which would render the claims allowable is available, a summary thereof must be attached.)

It is not necessary for applicant to provide a separate record of the substance of the interview.

Unless the paragraph above has been checked to indicate to the contrary, A FORMAL WRITTEN REPLY TO THE LAST OFFICE ACTION IS NOT WAIVED AND MUST INCLUDE THE SUBSTANCE OF THE INTERVIEW. (See MPEP Section 713.04). If a reply to the last Office action has not been filed, APPLICANT IS GIVEN ONE MONTH FROM THIS INTERVIEW DATE TO FILE A STATEMENT OF THE SUBSTANCE OF THE INTERVIEW.

Examiner Note: You must sign this form unless it is an attachment to another form.